



Material Content Data Sheet



Sales Product Name		SPA04N60C3		Issued		29. August 2013			
MA#		MA000448274							
Package		PG-TO220-3-111		Weight*		2265.90 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.279	0.14	0.14	1447	1447	
leadframe	non noble metal	iron	7439-89-6	1.120	0.05		494		
	inorganic material	phosphorus	7723-14-0	0.336	0.01		148		
	non noble metal	copper	7440-50-8	1118.332	49.36	49.42	493544	494187	
wire	non noble metal	aluminium	7429-90-5	0.720	0.03	0.03	318	318	
encapsulation	organic material	carbon black	1333-86-4	2.265	0.10		1000		
	plastics	epoxy resin	-	212.895	9.40		93955		
	inorganic material	silicondioxide	60676-86-0	917.259	40.48	49.98	404807	499762	
leadfinish	non noble metal	tin	7440-31-5	7.942	0.35	0.35	3505	3505	
plating	non noble metal	nickel	7440-02-0	0.305	0.01		135		
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	0	135	
solder	non noble metal	tin	7440-31-5	0.952	0.04		420		
	noble metal	silver	7440-22-4	0.366	0.02		162		
	non noble metal	antimony	7440-36-0	0.147	0.01	0.07	65	647	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

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